

SOT1799-6

CFM6F, ceramic flange mount flat package; 6 terminals; 4.445 mm pitch, 9.78 mm x 20.58 mm x 3.75 mm body

9 July 2019

Package information

1 Package summary

| | |
|--------------------------------|----------------------------------|
| Terminal position code | D (double) |
| Package type descriptive code | CFM6F |
| Package style descriptive code | CFMF (ceramic flange mount flat) |
| Package body material type | C (ceramic) |
| Mounting method type | S (surface mount) |
| Issue date | 14-08-2018 |
| Manufacturer package code | 98ASA01208D |

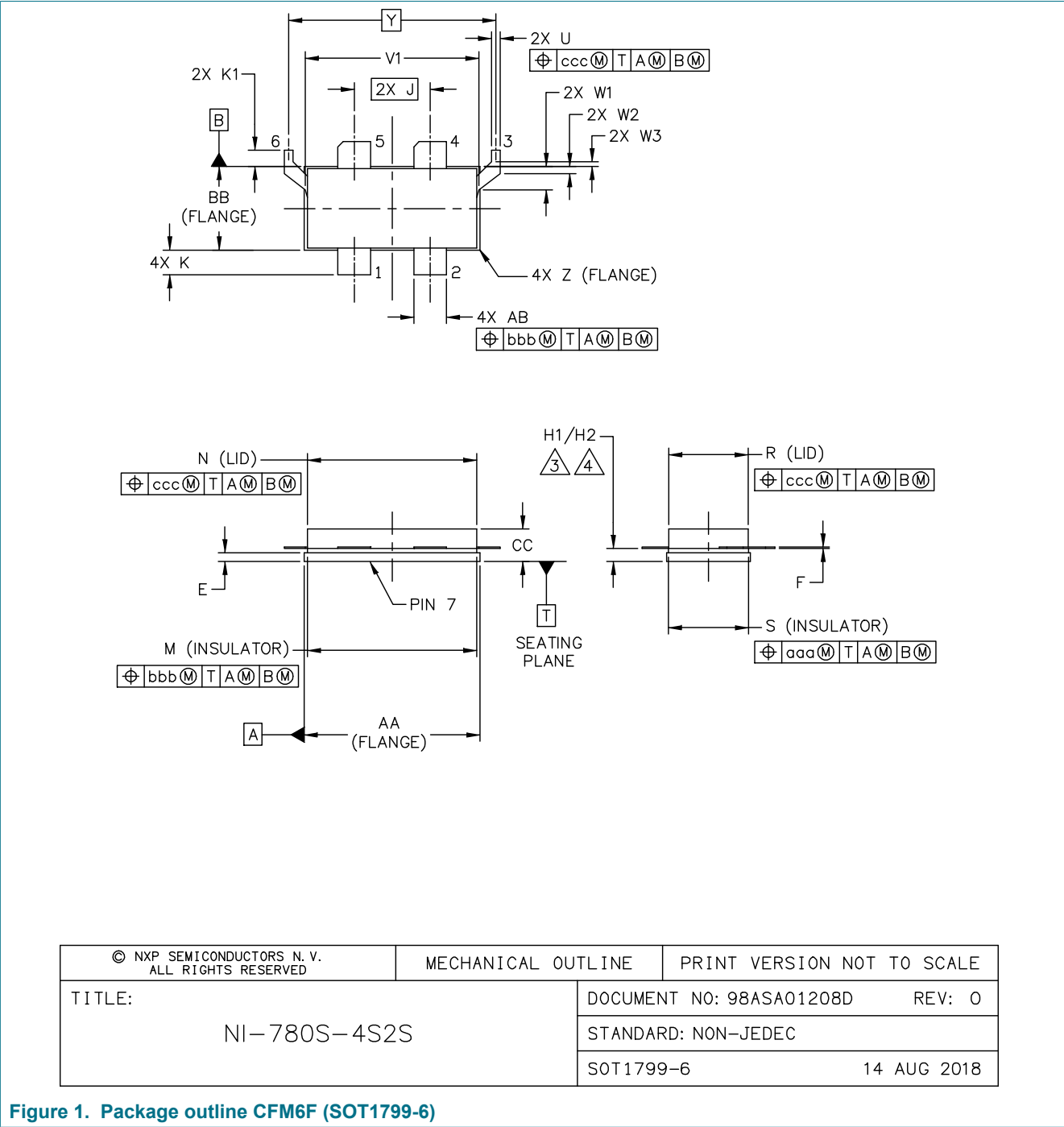
Table 1. Package summary

| Parameter | Min | Nom | Max | Unit |
|--------------------------------|-------|-------|------|------|
| package length | 9.65 | 9.78 | 9.91 | mm |
| package width | 20.45 | 20.58 | 20.7 | mm |
| package height | 3.18 | 3.75 | 4.32 | mm |
| nominal pitch | - | 4.445 | - | mm |
| actual quantity of termination | - | 6 | - | |



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2 Package outline



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NOTES:

- 1. CONTROLLING DIMENSION: INCH.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.

3. DIMENSIONS H1 AND H2 ARE MEASURED .030 INCH (0.762 MM) AWAY FROM FLANGE PARALLEL TO DATUM B TO CLEAR EPOXY FLOW OUT. H1 APPLIES TO PINS 1, 2, 4 & 5. H2 APPLIES TO PINS 3 & 6.

| DIM | INCH | | MILLIMETER | | DIM | INCH | | MILLIMETER | |
|-----|----------|-------|------------|-------|-----|----------|-------|------------|-------|
| | MIN | MAX | MIN | MAX | | MIN | MAX | MIN | MAX |
| AA | .805 | .815 | 20.45 | 20.70 | R | .365 | .375 | 9.27 | 9.53 |
| BB | .380 | .390 | 9.65 | 9.91 | S | .365 | .375 | 9.27 | 9.53 |
| CC | .125 | .170 | 3.18 | 4.32 | U | .035 | .045 | 0.89 | 1.14 |
| E | .035 | .045 | 0.89 | 1.14 | V1 | .795 | .805 | 20.19 | 20.45 |
| F | .004 | .007 | 0.10 | 0.18 | W1 | .0975 | .1175 | 2.48 | 2.98 |
| H1 | .057 | .067 | 1.45 | 1.70 | W2 | .0225 | .0425 | 0.57 | 1.08 |
| H2 | .054 | .070 | 1.37 | 1.78 | W3 | .0125 | .0325 | 0.32 | 0.83 |
| J | .350 BSC | | 8.89 BSC | | Y | .956 BSC | | 24.28 BSC | |
| K | .0995 | .1295 | 2.53 | 3.29 | Z | R.000 | R.040 | R0.00 | R1.02 |
| K1 | .070 | .090 | 1.78 | 2.29 | AB | .145 | .155 | 3.68 | 3.94 |
| M | .774 | .786 | 19.66 | 19.96 | aaa | .005 | | 0.13 | |
| N | .772 | .788 | 19.61 | 20.02 | bbb | .010 | | 0.25 | |
| | | | | | ccc | .015 | | 0.38 | |

| | | | |
|---|--|--------------------------------------|----------------------------|
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| TITLE: NI-780S-4S2S | | DOCUMENT NO: 98ASA01208D REV: 0 | |
| | | STANDARD: NON-JEDEC | |
| | | SOT1799-6 | 14 AUG 2018 |

Figure 2. Package outline note CFM6F (SOT1799-6)

3 Legal information

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body

Contents

| | | |
|---|-------------------------|---|
| 1 | Package summary | 1 |
| 2 | Package outline | 2 |
| 3 | Legal information | 4 |